

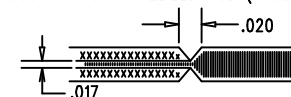
REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	PRODUCTION	JOHN C.	09-17-12

LAYER STRUCTURE



NOTES: UNLESS OTHERWISE SPECIFIED

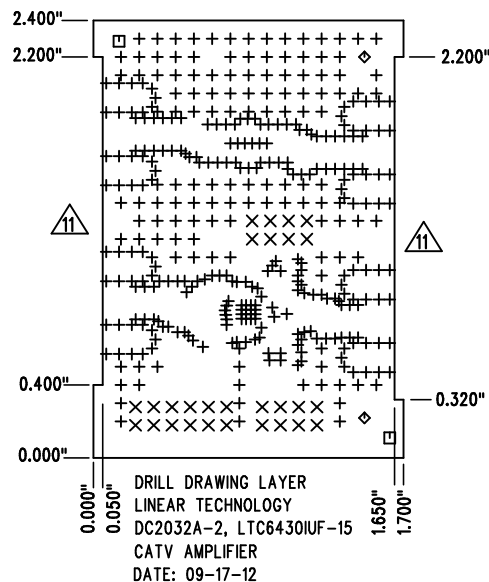
- FAB PER IPC-A-600.
- MATERIAL: -LEAD FREE ASSEMBLY COMPLIANT, NELCO-N4000-13EP
-FINISHED THICKNESS TO BE 0.062" +/- .005"
-TOTAL OF 4 LAYERS WITH 2 OZ. CU ON THE OUTER LAYERS AND 1 OZ. CU ON THE INNER LAYERS.
-FLAMMABILITY RATING: 94 V-0 MINIMUM.
- SIZE: CUT TO DIMENSIONS AND TOLERANCES SHOWN.
0.00" ARE PRIMARY DATUMS.
- DRILLING: -DRILL HOLES PER SCHEDULE. PLATE THROUGH HOLES WITH COPPER, 0.001" THICK MIN.
-ALL HOLE SIZES ARE SPECIFIED AFTER PLATING.
-HOLE LOCATION TOLERANCES ARE +/-0.003" IN RELATION TO CENTER
- FINISH: -SMOBC USING LPI BOTH SIDES, COLOR GREEN.
-GOLD IMMERSION BOTH SIDES.
-FOR SILKSCREENS: USE WHITE NON-CONDUCTIVE INK.
- DO NOT ALTER ARTWORK e.g. TO ADD LOGO OR DATE CODE.
PAD SIZE CAN BE MODIFIED TO MEET END FINISH.
- PCBS ARE TO BE RoHS COMPLIANT.
- SCORING FOR PANELIZED PCB (PRODUCTION FAB ONLY):



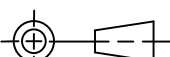

- CONTROLLED 75 OHM +/-5% IMPEDANCE FOR LAYERS 1-2 USING 0.022" TRACE

△10. SUBJECT TO CHANGE BY MANUFACTURER, DEPENDING ON DIELECTRIC CONSTANT DEVIATIONS. PLEASE CONSULT LTC.

△11. INNER AND OUTER LAYER COPPER SHALL BE EXPOSED ALONG BOARD EDGES. DO NOT MODIFY INNER LAYER COPPER BACKOFF OUTLINE (SMA CONNECTOR).



SIZE	QTY	SYM	PLATED	TOL
0.008	381	+	YES	+/-0.003
0.035	28	×	YES	+/-0.003
0.07	2	□	NO	+/-0.003
0.066	2	◇	YES	+/-0.003

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES: 0.XX" = ±0.01" 0.XXX" = ±0.005" INTERPRET DIM AND TOL PER ASME Y14.5M-1994 THIRD ANGLE PROJECTION 	APPROVALS		 LINEAR TECHNOLOGY 1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY	
	PCB DES.	AK		
	APP ENG.	JOHN C.		
	TITLE: FABRICATION DRAWING			
	CATV AMPLIFIER			
	SIZE N/A	IC NO. LTC6430IUF-15 DEMO CIRCUIT 2032A		REV 2
	FILENAME: DC2032A-2.PCB			SHT 1 OF 1